

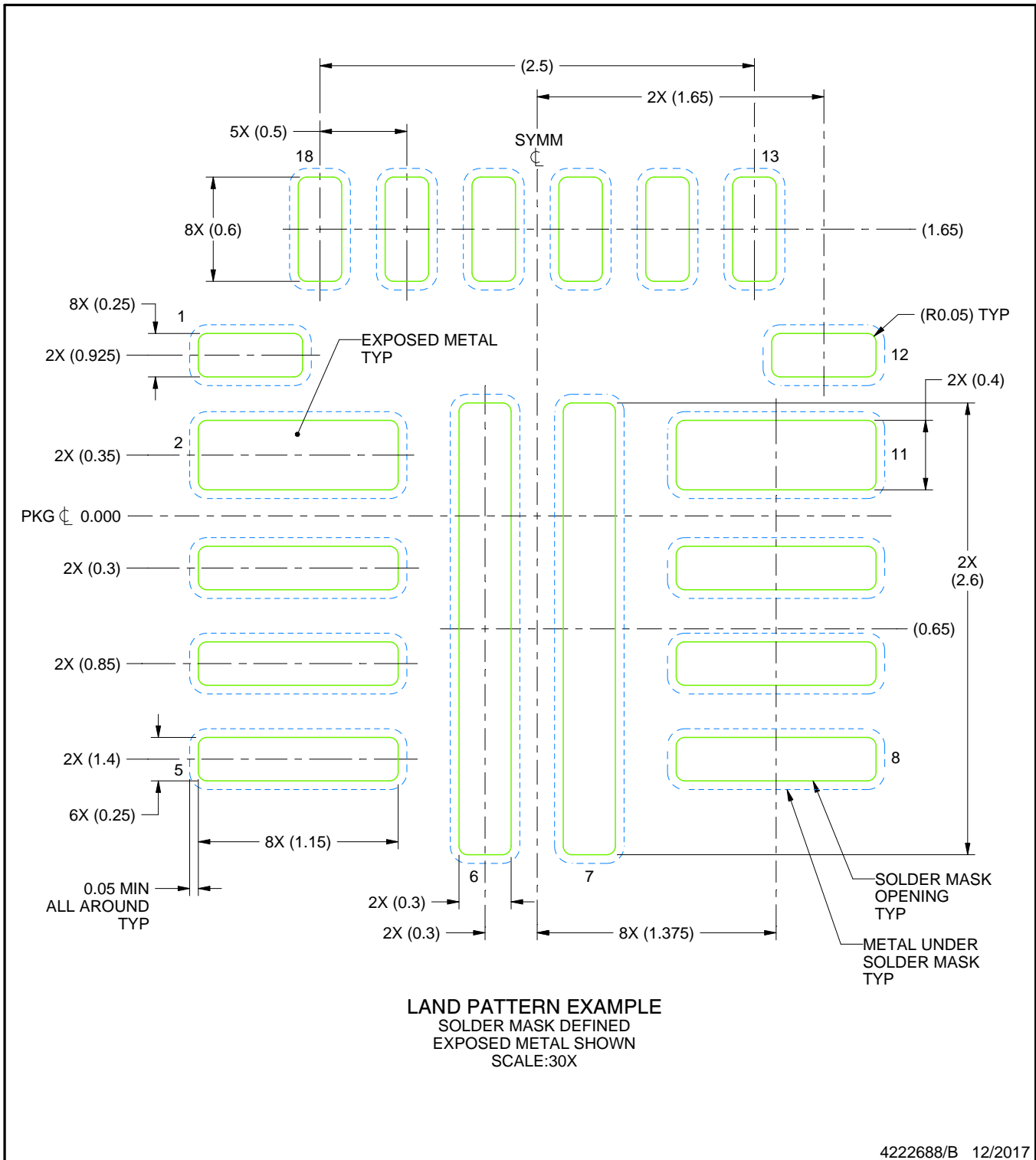


# EXAMPLE BOARD LAYOUT

RNN0018A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

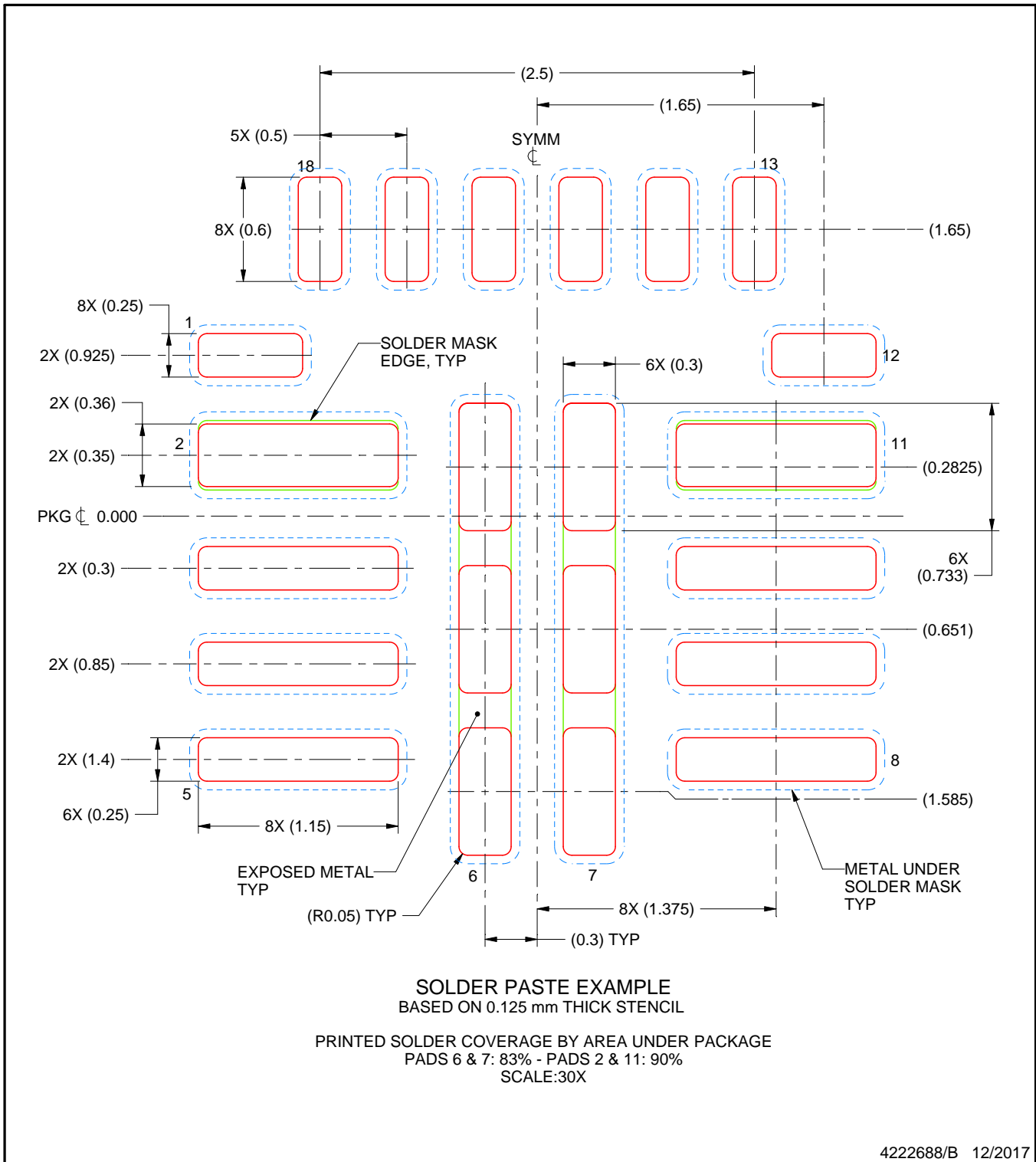
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).
- Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

RNN0018A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. For alternate stencil design recommendations, see IPC-7525 or board assembly site preference.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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